

## Electronic Patent Application Fee Transmittal

Application Number:	10576639
Filing Date:	
Title of Invention:	Method for Gluing a Circuit Component to a Circuit Substrate
First Named Inventor/Applicant Name:	Willbald Konrath
Filer:	Stephen A. Herrera/Laura Wade
Attorney Docket Number:	5577-006

Filed as Large Entity

### **U.S. National Stage under 35 USC 371 Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
Late filing fee for oath or declaration	1051	1	130	130
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>130</b>